# Product Change Notification: MFOL-05ZTBD969

## Date:

12-Mar-2025

## Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors

## Notification Subject:

CCB 6634 Cancellation Notice: For the qualification of Panel Level Package (PLP) packaging process technology available in 20L VQFN and 16L QFN (3x3x0.9mm), 20L QFN (4x4x0.9mm), 16L, 20L and 28L VQFN (4x4x1.0mm), 40L VQFN, 40L and 20L QFN (5x5x0.9mm) packages at NEPL assembly site.

## Affected CPNs:

**MFOL-05ZTBD969_Affected_CPN_03122025.pdf**
**MFOL-05ZTBD969_Affected_CPN_03122025.csv**

**PCN Status:** Cancellation Notification

**PCN Type:** Manufacturing Change

**Description of Change:** This qualification was initially performed to qualify Panel Level Package (PLP) packaging process technology available in 20L VQFN and 16L QFN (3x3x0.9mm), 20L QFN (4x4x0.9mm), 16L, 20L and 28L VQFN (4x4x1.0mm), 40L VQFN, 40L and 20L QFN (5x5x0.9mm) packages at NEPL assembly site.

**Impacts to Datasheet:** Not Applicable

**Change Impact:** Not Applicable

**Reason for Change:** Microchip has decided to not qualify Panel Level Package (PLP) packaging process technology available in 20L VQFN and 16L QFN (3x3x0.9mm), 20L QFN (4x4x0.9mm), 16L, 20L and 28L VQFN (4x4x1.0mm), 40L VQFN, 40L and 20L QFN (5x5x0.9mm) packages at NEPL assembly site.

**Change Implementation Status:** Not Applicable

**Estimated Qualification Completion Date:** Not Applicable

**Revision History:**

November 06, 2023: Issued initial notification.

March 08, 2024: Reissued initial notification. Updated the affected parts list. Updated the mold compound from CEL-400ZHF40-PLM2KG to X8511AU-IMP1 (1st mold) / X8511CUB-AP1 (2nd mold), and EME-QXG01 (1st & 2nd mold), and updated die attach from BSP 140 to BSP 1100 in the pre- and post- change summary table. Updated the estimated qualification completion date to be on March 2024.

March 15, 2024: Reissued initial notification to update the Qual Plan file name.

April 16, 2024: Issued final notification. Added estimated first ship date on May 01, 2024 and updated qual report completion on May 31, 2024. Updated the affected CPN list to add newly released parts. Updated post change mold compound material to NEPL Proprietary.

December 10, 2024: Re-issued final notification. Attached the qualification report. Updated the affected CPN list to add newly released parts. Removed CPNs PIC18F16Q20-I/REBC01 and PIC18F16Q20T-I/REBC01 on the affected parts list due to being EOL'd. Removed 16L QFN (4x4x0.9mm) package and included 20L VQFN (4x4x1.0mm) package in the Notification subject.

March 12, 2025: Issued cancellation notice.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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